



[Home](#) > [Products](#) > [Memory](#) > [Nonvolatile Products](#) > [nvSRAM Parallel](#) > CY14V256LA-BA35XIT

CY14V256LA-BA35XIT Status: In Production

 [Alert me about changes to this product](#)

 [SHARE](#)   

[Datasheet](#)

[Quality and RoHS](#)

[Support and Community](#)

[Inventory](#)

[Technical Documents](#)

[Packaging/Ordering](#)

[Related Products](#)



CY14V256LA-BA35XIT

Automotive Qualified	N
Min. Operating Voltage (V)	2.70
Max. Operating Voltage (V)	3.60
Min. Operating Temp. (°C)	-40
Max. Operating Temp. (°C)	85
Frequency (MHz)	N/A
Temp. Classification	Industrial
Max. Operating VCCQ (V)	1.95
Min. Operating VCCQ (V)	1.65
Speed (ns)	35
Density (Kb)	256
Organization (X x Y)	32Kb x 8

Pricing & Inventory Availability

1-10 unit Price*	11-100 unit Price*	101-1000 unit Price*	1001 + unit Price*

Availability	Quantity	Ships In	Order Now

* Prices are shown in United States dollars and are for budgetary use only.

Packaging / Ordering

Package	FBGA
No. of Pins	48
Package Dimensions	393 L X 1.2 H X 236 W (Mils)
Package Weight	119.15 (mgs)
Package Cross Section Drawing	Download
Package Carrier	REEL
Package Carrier Drawing / Orientation	Tape Drawing, Reel Drawing, Package Orientation
Standard Pack Quantity	2000
Minimum Order Quantity (MOQ)	2000
Order Increment	2000
Estimated Lead Time (days)	56
HTS Code	8542.32.0040
ECCN	3A991

ECCN Suball	(B.2.A.)
-------------	----------

Quality and RoHS	
Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Sn/Ag/Cu
Marking	Cypress Marking Format
Package Material Declaration 48 - BGA (6X10X1.2MM) PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET Last Update: 07/09/2012	
IPC 1752 Material Declaration IPC-1752-2_V1.1_BGA 48 (6 X 8 MM) _ASET_SNAGCU(SAC405) Last Update: 07/04/2012	
RoHS Analysis Certificates (CoA) PACKAGE ROHS ANALYSIS REPORT - BGA (BK/BP 36, 42, 48, 96) (BW 96,100,119,144,165,172,196,209,256,400) USING MOLD COMPOUND KEG2270, ADHESIVE 2025D, SAC405 - ASE TAIWAN ASSEMBLY Last Update: 07/04/2012	
RoHS Analysis Certificates (CoA) for Direct Materials Please click here	
Device Qualification Reports  FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report. Please click here .	

Technical Documents
Application Notes (11) AN43593 - Storage Capacitor (V_{CAP}) Options for Cypress nvSRAM Last Update: 21/03/2013 AN55663 - Migrating from CY14E256L/STK14C88 to CY14E256LA Last Update: 18/03/2013 AN6068 - Replacing 4Mbit (256K x16) MRAM with Cypress nvSRAM Last Update: 13/03/2013 AN43380 - HSR Operation in nvSRAMs Last Update: 03/10/2012 Show More
Product Information Notice (PIN) (1) PIN135200 Last Update: 21/03/2013

Support and Community
Cypress Developer Community™ Forums Blogs Support Knowledge Base Product Training